

### **IN THE SPECIFICATION**

Please amend the specification as follows:

**The paragraph beginning at page 1, line 11 is amended as follows:**

The semiconductor industry has seen tremendous advances in technology in recent years that have permitted dramatic increases in circuit density and complexity, and equally dramatic decreases in power consumption and package sizes. Present semiconductor technology now permits single-chip microprocessors with many millions of transistors, operating at speeds of tens (or even hundreds) of MIPS (millions of instructions per second), to be packaged in relatively small, air-cooled semiconductor device packages. A direct by-product of higher density circuits with smaller feature sizes is smaller die and, therefore, a higher number of die formed on a wafer. Typically, a number of identical electronic devices are formed on a single wafer. In some instances, up to several thousand identical devices are formed on a wafer. More commonly, 200 to 300 identical devices are formed on a wafer. Once formed, each of the devices is electrically tested ~~an~~ and sorted. Next, the wafer is sliced and diced to produce individual wafer portions known as die or chips. Each die or chip contains an individual device, such as an integrated circuit, a microprocessor, or other electronic device. Each die also includes leads, such as pins or balls, which are formed on the surface of the die.

**The paragraph beginning at page 6, line 21 is amended as follows:**

Now turning briefly to FIG. 5, which is a top view of a wafer 520 having a laser scribe area formed as shown in FIG. 4, it can be seen that the laser scribe area includes a first laser scribe 531, represented by a dark line and a second laser scribe line 532 represented by a darker gray line, and a third laser scribe line 533, which is formed between the laser scribe line 531 and the laser scribe line 532. The laser scribe line 533 is a lighter gray than either of the laser scribe lines 531 or 532. It should be noted that the shades of gray shown in FIG. [[6]] 5 are merely for the sake of illustrating the sequence of laser scribe lines that form the laser scribe area 530.